



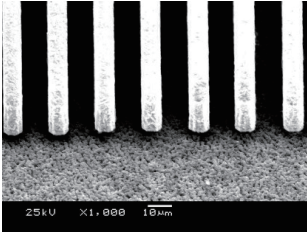
熱硬化型層間絶縁材料

Zaristo 125/Zaristo517X

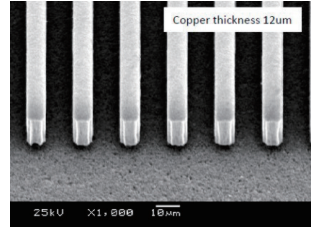
Thermal curable Build up Material for SAP

特長 Features

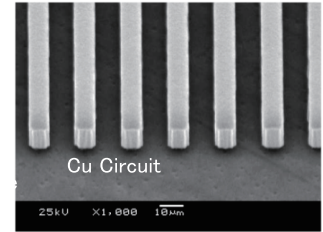
- SAP対応 Suitable for Conventional SAP
- 高BHAIST耐性 Excellent LtL & L/S BHAIST stability



Conventional BUM DF



Zaristo 125



Zaristo 517X

Fig. FLS(L/S=10/10um) on Zaristo

Test Items	Unit	Zaristo125	Zaristo517X
Tg(TMA)	deg.C	165 - 175	165 - 175
CTE α 1	ppm	25 - 30	17
Young' Modulus	GPa	7 - 8	11 - 12
Dk (10GHz,SPDR)		3.4	3.4
Df (10GHz,SPDR)		0.015	0.004 - 0.005
Peel strength Ra after Desmear	N/cm um	>5.0 0.25 ~ 0.40	4.0 0.2 ~ 0.25

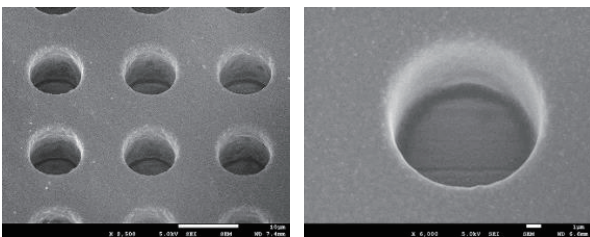
感光性層間絶縁材料

PVI-3 HR100S

Photo Imageable Dielectric Material PVI-3 HR100S

特長 Features

- 高解像性 Smaller Via opening
- 高密着性 Excellent Peel Strength
- 高絶縁信頼性 High insulation reliability
- ドライフィルムタイプ Dry Film type



Resolution

10um Via / Thickness 10um

Test Items	Unit	PVI-3 HR100S
Tg(TMA)	deg.C	180 - 185
CTE α 1	ppm	40 - 45
Young' Modulus	GPa	3.0 - 3.5
Tensile Strength	MPa	75 - 80
Elongation	%	15 - 20



TAIYO INK MFG. CO., LTD.